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(54) **Title**: METHOD OF MANUFACTURING WAFER LAMINATED BODY, DEVICE OF MANUFACTURING WAFER LAMINATED BODY, WAFER LAMINATED BODY, METHOD OF PEELING SUPPORT BODY, AND METHOD OF MANUFACTURING WAFER

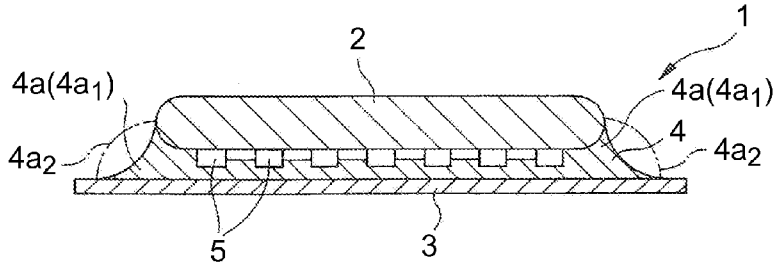



*Fig. 1*

(57) **Abstract**: The present disclosure is to provide a method of manufacturing a wafer laminated body, a device for manufacturing a wafer laminated body, a wafer laminated body, a method of peeling a support body, and a method for manufacturing a wafer, all of which are capable of improving the grinding characteristic of the reverse surface of a wafer. A method includes sucking a wafer (2) onto a wafer suction table situated above, sucking a support body (3) onto a support body suction table situated below, and arranging the wafer (2) and the support body (3) in opposition to each other in a vertical direction; applying a liquid adhesive resin to an opposing face of the support body (3) opposed to the wafer (2) for forming a adhesive agent layer; causing the wafer (2) and the support body (3) to approach each other while maintaining parallelism therebetween, and applying pressure to the adhesive resin interposed therebetween and spreading the adhesive resin to thereby fill a space between the wafer (2) and the support body (3) with the adhesive resin, and to form a resin projecting portion (4a) on the outer circumference of the wafer

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